



Appl. No. 10/735,355

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. .... 10/735,355  
Filing Date ..... December 12, 2003  
Inventor ..... Zhongze Wang  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2812  
Examiner ..... Jennifer M. Kennedy  
Attorney's Docket No. .... MI22-2457  
Customer No. .... 021567  
Title: Wafer Bonding Method of Forming Silicon-on-Insulator Comprising Integrated  
Circuitry

**RESPONSE TO APRIL 22, 2005 OFFICE ACTION**

To: Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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**AMENDMENTS**

**Introductory Comments**

In reply to the Office Action of April 22, 2005, applicant amends and remarks as follows.